

**AMENDMENTS TO THE CLAIMS:**

**Please cancel claims 1-6, 26-35, 37-39 and 41-45 without prejudice or disclaimer.**

1-6. (Canceled)

7. (Withdrawn) A method of making a light emitting apparatus, comprising:

providing a light-transmitting portion that includes a recess to house a semiconductor light emitting element, the light-transmitting portion comprising a light transmitting material and the recess being provided with a phosphor layer that is formed on a surface of the recess;

forming an electrode of metal material;

mounting the semiconductor light emitting element on the electrode;

positioning the light-transmitting portion adjacent to the electrode such that said semiconductor light emitting element is housed in said recess; and

bonding the light-transmitting portion onto the electrode such that the phosphor layer of the recess surrounds an upper portion of the semiconductor light emitting element, said light transmitting portion being affixed to said electrode by a sealant formed on said light emitting element,

wherein said light-transmitting portion comprises a convex portion and said electrode comprises a concave portion which engages with said convex portion to allow the light-transmitting portion to be positioned on the electrode.

8. (Withdrawn) The method according to claim 7, wherein the phosphor layer is formed by spraying a phosphor material on the surface of the recess after forming the recess by molding.

9. (Withdrawn) The method according to claim 7, wherein the electrode comprises a lead electrode provided on the surface of a submount member of high thermal

conductivity.

10. (Withdrawn) The method according to claim 7, wherein the electrode comprises a copper-foil electrode provided through an insulation layer on the surface of a base member of high thermal conductivity.

11. (Withdrawn) The method according to claim 7, wherein the semiconductor light emitting element is flip-chip bonded onto the electrode.

12-25. (Canceled)

26-35. (Canceled)

36. (Withdrawn) The method according to claim 7, further comprising:

forming said sealant between said light emitting element and said phosphor layer, for sealing said light emitting element, said forming said sealant comprising:

injecting said sealant into said recess; and

fixing said light transmitting portion onto said light emitting element such that said light emitting element is sealed with said sealant.

37-39. (Canceled)

40. (Withdrawn) The method according to claim 7, wherein said pre-molded light-transmitting portion further comprises a positioning portion to allow said pre-molded light-transmitting portion to be precisely positioned to said semiconductor light emitting element.

41-45. (Canceled)

46. (New) A light-emitting apparatus, comprising:

a semiconductor light-emitting element that emits light with a predetermined wavelength; and

an external lens having a light convergence shape to converge light emitted from the light-emitting element, said external lens comprising:

a recess to house the semiconductor light-emitting element; and

a phosphor layer portion that is formed on a surface of the recess, the phosphor layer portion including a phosphor to be excited by irradiating light emitted from the semiconductor light-emitting element,

wherein the recess is closely disposed surrounding the light-emitting element such that the light convergence shape converges light radiated from the phosphor layer portion into a spot of light.

47. (New) The light-emitting apparatus according to claim 46, wherein the semiconductor light-emitting element comprises a flip-chip type light-emitting diode (LED) element that emits light from its light emission surface located on the opposite side of its mounting surface.

48. (New) The light-emitting apparatus according to claim 46, wherein the recess is located close to the semiconductor light-emitting element along the profile of the semiconductor light-emitting element.

49. (New) The light-emitting apparatus according to claim 46, wherein the semiconductor light-emitting element comprises a plurality of light-emitting diode (LED) elements which are disposed in a predetermined arrangement.

50. (New) The light-emitting apparatus according to claim 46, wherein the semiconductor light-emitting element comprises a plurality of light-emitting diode (LED) elements which have different emission wavelengths and are disposed in a predetermined arrangement.

51. (New) The light-emitting apparatus according to claim 46, wherein the phosphor layer portion is formed on an entire surface of the recess.
52. (New) The light-emitting apparatus according to claim 46, wherein the phosphor layer portion comprises a uniform thickness.
53. (New) The light-emitting apparatus according to claim 46, wherein a horizontal cross section of the recess comprises one of a circular shape and a rectangular shape.
54. (New) The light-emitting apparatus according to claim 46, further comprising:  
an electrode, said light-emitting element being formed on said electrode, and  
said external lens being affixed to said electrode by a sealant formed on said light-emitting element.
55. (New) The light-emitting apparatus according to claim 54, wherein said external lens comprises:  
a convex portion and a bottom surface which is formed opposite the convex portion and includes said recess.
56. (New) The light-emitting apparatus according to claim 55, further comprising:  
a submount formed on a concave portion of said electrode, a wiring pattern being formed on a surface of said submount and said light-emitting element being mounted on said wiring pattern.
57. (New) The light-emitting apparatus according to claim 56, wherein said electrode comprises a plurality of leads, and said submount is formed on said plurality of leads.
58. (New) The light-emitting apparatus according to claim 57, wherein a gap is formed between a surface of said phosphor layer portion and said light-emitting element, said sealant filling said gap.